This presentation contains certain forward-looking statements. These forward-looking statements may be identified by words such as ‘believes,’ ‘expects,’ ‘anticipates,’ ‘projects,’ ‘intends,’ ‘should,’ ‘seeks,’ ‘estimates,’ ‘future’ or similar expressions or by discussion of, among other things, strategy, goals, plans or intentions. These statements include financial projections and estimates and their underlying assumptions, statements regarding plans, objectives and expectations with respect to future operations, products and services, and statements regarding future performance. Actual results may differ materially in the future from those reflected in forward-looking statements contained in this document, due to various factors. These risks and uncertainties include those discussed under “Cautionary Statement Concerning Forward Looking Statements” and “Risk Factors” in the prospectus included in the registration statement on Form F-4 that ChipMOS filed with the U.S. SEC.
ChipMOS Group Snapshot

Overview
- Founded: 1997
- Headquarters: Hsinchu, Taiwan
- Ticker Symbol: TWSE: 8150.TW, NASDAQ: IMOS
- Employees:
  - Taiwan: 5,560
  - China: 650

Manufacturing footprint in China & Taiwan
- Shanghai, China
  - ChipMOS Shanghai
- Hsinchu, Taiwan
  - ChipMOS Taiwan
- Tainan, Taiwan
  - ChipMOS Taiwan

Key milestones
- 2000
  - Started TCP package for LCD driver semiconductor and 12" wafer assembly and testing business
- 2007
  - Acquired 100% interest in ChipMOS Taiwan
- 2010
  - Acquired LCD assets of SPIL
  - SPIL became a strategic shareholder of ChipMOS Taiwan
- 2011
  - Set up 12" Gold bumping, Cu RDL, MCP, Cu pillar, MCB bumping and WLCSP line
- 2014
  - Listed ChipMOS Taiwan on TWSE
  - Announced the merger between ChipMOS Taiwan and ThaiLin
  - Invested in JMC and Ryowa
- 2015
  - ChipMOS Taiwan merged ThaiLin(2)
  - Announced private placement with Tsinghua Unigroup
- 2016
  - ChipMOS Taiwan merged ChipMOS Bermuda and issued ADS (Nasdaq Ticker: IMOS)
- 2017
  - ChipMOS Taiwan JV with Tsinghua Unigroup (3)

(1) As of December 31, 2016
(2) ThaiLin was listed on OTC since Oct 2000, and was de-listed in Jun 2015
(3) ChipMOS Taiwan is authorized managing ChipMOS Shanghai
ChipMOS – Industry Leader in Outsourced Semiconductor Assembly & Test

1. Leveraging Leadership Position and Track Record as Top Service Provider

2. Focused on Growth in Key Markets, including LCD Driver & Memory Markets

3. Joint-Venture to Monetize Shanghai Operation, Drive China Growth and Deliver Increased Profitability in 2017 and Beyond

4. Start to Realize Significant Financial and Operational Benefits in 2017 from Now Completed Corporate Structure Streamlining

5. Robust Technology Roadmap Supports Multiple Growth Vectors, Including Finger Print Sensors, MEMS, Mixed-Signal, and Power IC Market Segments

6. Proven Senior Management Team Executing on Right Business Strategy
Focused on Higher Margin Growth Markets

- Focus on specialty end markets
- Leading-edge turn-key solutions for high-growth applications
- Focused core technology drives innovation and cost-savings for customers
Revenue Breakdown

Consolidated Revenue

2013 2014 2015 2016
19,361.9 22,005.1 19,869.4 18,387.6

(1) Since 2015, the Consolidated Revenue is not including ChipMOS Shanghai

2016 Revenue Breakdown: 2016 Revenue NTD $ 18,387.6 M元

By Manufacturing Segments
- Package Test 15.3%
- Wafer Sort 9.6%
- Bumping (incl. RDL/MEMS/PM) 16.3%
- LCD Driver 26.8%
- Assembly 32.0%

By Products
- Bumping (incl. RDL/MEMS/PM) 15.9%
- LCD Driver 27.1%
- Logic/Mixed Signal 8.9%
- SRAM 0.8%
- Flash 15.9%
- Niche DRAM 17.3%
- Commodity DRAM 14.1%
Q416 Revenue Breakdown by Segment (unaudited)

By Manufacturing Segments

- **Assembly**: 31.8%
- **LCD Driver**: 24.6%
- **Wafer Sort**: 11.0%
- **Package Test**: 15.7%
- **Bumping (incl. RDL/MEMS/PM)**: 16.9%

Q3'16 Q4'16

- **LCD Driver**
  - QoQ -6.0%
- **Assembly**
  - QoQ -3.8%
- **WS**
  - QoQ 10.1%
- **Package Test**
  - QoQ 3.2%
Q416 Revenue Breakdown by Product (unaudited)

By Products

- Bumping (incl. RDL/MEMS/PM) 16.4%
- LCD Driver 25.4%
- Logic/Mixed Signal 10.1%
- SRAM 0.8%
- Flash 18.0%
- Niche DRAM 16.1%
- Commodity DRAM 13.2%

QoQ comparisons:
- Niche DRAM: QoQ -9.4%
- Commodity DRAM: QoQ -9.4%
- LCD Driver: QoQ -4.9%
- Logic/Mixed Signal: QoQ 9.1%
- SRAM: QoQ 9.0%
- Flash: QoQ 14.4%
Turnkey, High-yield, OSAT Partner of Choice

- Offer turn-key solutions for core technology product segments
- Dedicated OSAT capacity and strategically focused on collaboration-driven growth
- Leverage current partnerships to capture new customers
- Targeting mixed-signal, finger print sensor and MEMS for expansion

<table>
<thead>
<tr>
<th>Product Offering</th>
<th>Bumping /RDL</th>
<th>Wafer Testing</th>
<th>Assembly/Packaging</th>
<th>Product Testing</th>
<th>Key End Markets</th>
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</thead>
<tbody>
<tr>
<td>LCD Driver</td>
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<td>Logic/Mixed Signal</td>
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</table>
Well-positioned to Capture the LCD driver Outsourcing Markets

- Global proliferation of digital broadcasting fosters adoption of LCD TVs
- Widespread use of LCD drivers in electronic products
- High resolution / function integration to drive LCD driver growth
- ChipMOS is one of the major players in the LCD driver bumping and test / assembly market
- Focused investment in capacity expansion in growth market based on technology advancement
- Develop bumping technology for non-driver applications to capture new business and enable turn-key offerings in mixed signal, IoT, sensor markets
UHD (4K2K) LCD TV Growth Drives COF Capacity Demand

- UHD/4K propels significant memory/storage market growth in set top boxes, TV, home entertainment system
- Market penetration of UHD panel accelerating, GOA(Gate On Array) affecting gate driver demand for small panels
- Increase in LCDD COF demand driven by UHD and AMOLED

ChipMOS preparing capacity to capture market growth

Source: Nomura estimates; Himax
Extend Bumping Core Competency to Grow New Business

- 4K/UHD penetration rate at 3x faster than FHD/1080; To increase display driver output to meet both 4KTV and AMOLED demand

- Extending core competency to capture new market of Non-driver bumping products and provide turn key solutions for: Flip Chip, RDL, Advanced Memory, RDL, WLCSP, Power IC, etc.

![Graph showing Bumping Output]
Fingerprint sensor Demand Propelled by Mobile Products

- By offering both LGA and COF (tape based) products, ChipMOS is uniquely positioned by providing both types of packages to support FPS market growth.
- 10+ years of FPS(COF) packaging experience
- Full range of options support turn-key solutions with maximum technology extendibility

Source: Nomura estimates

Source: Nomura estimates
MEMS Market Growth Leads to Turn-key Service Opportunities

- MEMS industry growth driven mainly by applications such as smartphone, mobile consumers products, medical and automotive market
- Deliver Package and Wafer based products plus comprehensive test services, ChipMOS established itself as a turn-key OSAT provider to the growing MEMS market
- 6+ years record of executing magnetometer backend turn-key service for key customers
- Built capabilities to cover gyroscope, accelerometers & pressure sensors

MEMS Market Forecast (USD Billion)

Source: Yole Development
China JV: Catalyst for Significant Profitability Growth

- Strategic investors led by Tsinghua Unigroup have agreed to contribute US$72 million for a 55% stake in ChipMOS Shanghai. ChipMOS TECHNOLOGIES plans to re-invest US$70 million back into ChipMOS Shanghai in two tranches after the joint-venture closes to fund its CapEx.

- Upon regulatory approval, the strategic partners will then contribute another approximately US$75 million into ChipMOS Shanghai, of which approximately US$10.9 million will be from two strategic customers and employees.

- All together, ChipMOS Shanghai is expected to receive a total approximately US$155 million in funding by the end of 2017. Net net, strategic investors, led by Tsinghua Unigroup, will be investing a total of approximately RMB 1.1 billion into ChipMOS Shanghai.

- ChipMOS TECHNOLOGIES will own 45% of ChipMOS Shanghai on a go forward basis. There will be no minority interest post the JV closure.

- ChipMOS TECHNOLOGIES will recognize 45% of the profit generated by ChipMOS Shanghai.

- ChipMOS TECHNOLOGIES will not consolidate ChipMOS Shanghai post the JV closure. ChipMOS Shanghai will become a long-term investment of ChipMOS TECHNOLOGIES.

- ChipMOS is well positioned to capture the growth opportunities of the emerging semiconductor market in China
China JV: Catalyst for Significant Profitability Growth

Post-Transaction Pro-Forma Shareholding Structure

- ChipMOS BVI: 45.02%
- Unigroup Guowei: 48.00%
- Strategic Investors + Employees: 6.98%

ChipMOS Shanghai
ChipMOS Management Team with Deep Industry Experience

**Shih-Jye CHENG – Chairman & CEO**
- 32 Years of industry experience
- Former head of the back-end operation of Mosel
- Former Chairman of Chantek
- Former Chairman of AMCT
- Former board director of Ultima Electronics Corp
- MBA from Saginaw Valley State University

**Dr. Shou-Kang CHEN – CFO**
- 28 Years of industry experience
- IR officer, head of the finance division, and former head of strategy development, and head of the quality lab in the firm
- B.S. of Mining and Petroleum Engineering and M.S. and Ph.D. from the School of Mining, Metallurgy, Material Science of National Cheng Kung University

**Peter KU – Special Assistant**
- 43 Years of industry experience
- Former board director of ThaiLin
- Former President of Shanghai
- Former VP of ChipMOS Taiwan
- Former VP of Microchip Taiwan Branch
- M.S. of Electrical Engineering from National Cheng Kung University

**Lafair CHO – EVP**
- 23 Years of industry experience
- Former President of ThaiLin
- Former VP of the IC testing of ChipMOS Taiwan
- Former manager of production material control of Mosel
- M.S. of Industrial Management from National Cheng Kung University

**Steve CHENG – President of U.S.**
- 17 Years of industry experience
- Former President and CFO of ChipMOS U.S.A.
- B.S. of Business Banking and Insurance from Feng Chia University

**Dr. David WANG – VP of Strategy & IR**
- 34 Years of industry experience
- Former VP of Fibera
- Former Senior Director at Lam Research
- Former IBM's Microelectronics Senior Engineer/Manager
- M.S. and Ph.D. from the University of Michigan and B.S. of Science from Fu Jen University

**Paul YANG – President of Shanghai**
- 17 Years of industry experience
- Former VP of Test Production Group
- Former VP of the deputy assistant and mix-signal test division of ThaiLin
- M.S of Electrical Engineering from National Cheng Kung University
Financial Highlights
4Q16 Capital Expenditures (unaudited)

CapEx

4Q16 CapEx Breakdown

Testing 21%
LCD Driver 13%
Assembly 24%
Bumping 42%

(M NTD$)

2015 2016 Q3’16 Q4’16

3,644.6 3,123.3 979.9 964.0
4Q16 Capacity Utilization

Utilization Rate

Testing

Assembly

LCD Driver

Bumping

ChipMOS
1Q17 Business Outlook

- The Company expects 1Q17 revenue to be approximately 4% to 8% lower, as compared to 4Q16.

- The Company expects 1Q17 gross margin on a consolidated basis to be in the range of approximately 16% to 20%.

- Operating expenses are expected to be approximately 9% to 11% of revenues in 1Q17.
Company Website

- http://www.chipmos.com